

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2213960	test\$4 inspect\$4 edit\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/24 09:38
L2	633875	diode mim m-i-m second adj conduct\$4 adj (layer film) conduct\$4 adj insulat\$4 adj conduct\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/24 09:40
L3	12088	1 with 2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/24 09:40
L4	2228383	(microchip micro adj chip chip integrated adj circuit die ic semiconductor adj (device element structure component module) )	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/24 09:42
L5	1656	3 same 4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/24 09:44
L6	10240204	element structure component portion	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/24 09:44
L7	27783	1 adj 6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/24 09:45
L8	159	5 and 7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/24 09:49
L9	232	3.clm.	US-PGPUB	OR	ON	2005/09/24 09:50
L10	75309	4.clm.	US-PGPUB	OR	ON	2005/09/24 09:50
L11	948	7.clm.	US-PGPUB	OR	ON	2005/09/24 09:50
L12	9	9 and 10 and 11	US-PGPUB	OR	ON	2005/09/24 09:50
L13	2132982	silicon semiconductor	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/24 09:55

L14	299325	13.clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/24 09:55
L15	7	12 and 14	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/24 09:57
L16	7	(US-20040232522-\$ or US-20040232446-\$ or US-20030193051-\$ or US-20030153172-\$ or US-20030067314-\$ or US-20020187582-\$ or US-20020179930-\$).did.	US-PGPUB	OR	ON	2005/09/24 09:56
L17	7	16 and 1 and 13	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/24 10:10
L18	9	12 and 1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/24 10:51
L19	159	8 and 7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/24 11:29
L20	0	10/625010	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/24 12:09
L21	2	"20010049980"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/24 12:10
L22	2	"20010048980"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/24 12:10